

600V, 7A, Trench FS II Fast IGBT

General Description:

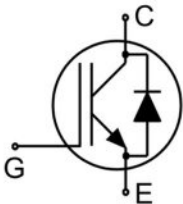
Using MJ's proprietary trench design and advanced FS (Field Stop) second generation technology, the 600V Trench FSII IGBT offers superior conduction and switching performances, and easy parallel operation;

Features

- ◆ Trench FSII Technology offering
- ◆ Very low $V_{CE(sat)}$
- ◆ High speed switching
- ◆ Positive temperature coefficient in $V_{CE(sat)}$
- ◆ Very tight parameter distribution
- ◆ High ruggedness, temperature stable behavior

Application

- ◆ Air Condition
- ◆ Inverters
- ◆ Motor drives



Schematic diagram



TO-252

Package Marking and Ordering Information

Device	Device Package	Device Marking
MJ07TD60BK	TO-252	MJ07TD60BK

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Value	Units
Collector-Emitter Voltage	V_{CES}	600	V
Gate- Emitter Voltage	V_{GES}	±30	V
Collector Current	I_C	14	A
Collector Current @Tc = 100 °C	I_C	7	A
Pulsed Collector Current, tp limited by Tjmax	I_{Cplus}	21	A
turn off safe operating area, VCE=600V, Tj=150°C	-	21	A
Diode Continuous Forward Current @Tc = 100 °C	I_F	7	A
Diode Maximum Forward Current	I_{FM}	21	A
Power Dissipation @ Tc = 25°C	P_D	87	W
Power Dissipation @Tc = 100 °C	P_D	43.5	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +175	°C
Maximum Temperature for Soldering	T_L	260	°C
Short circuit withstand time VGE=15.0V, VCC≤400V, Allowed number of short circuits<1000Time between short circuits:≥1.0s, Tj≤150°C	t_{sc}	5	us

Thermal Characteristic

Parameter	Symbol	Value	Units
Thermal Resistance, Junction to case for IGBT	$R_{\theta JC}$	1.71	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to case for Diode	$R_{\theta JC}$	2.50	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	62	$^{\circ}\text{C/W}$

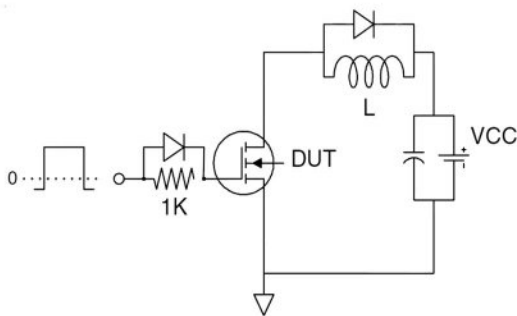
Electrical Characteristics (T_c=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Value			Units
				Min	Typ	Max	
Static Characteristics							
Collector-Emitter Breakdown Voltage	V _{(BR)CES}	V _{GE} =0V,I _{CE} =1mA		600	-	-	V
Collector-Emitter Leakage Current	I _{CES}	V _{GE} =0V,V _{CE} =600V		-	-	4	uA
Gate to Emitter Forward Leakage	I _{GES(F)}	V _{GE} =+30V,V _{CE} =0V		-	-	100	nA
Gate to Source Reverse Leakage	I _{GES(R)}	V _{GE} =-30V,V _{CE} =0V		-	-	100	nA
Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _C =5A V _{GE} =15V	T _J =25°C	-	1.7	1.9	V
			T _J =100°C	-	1.9	-	V
Gate Threshold Voltage	V _{GE(th)}	I _C =1mA, V _{CE} =V _{GE}		4.0	5.0	6.0	V
Dynamic Characteristics							
Input Capacitance	C _{ies}	V _{CE} =25V,V _{GE} =0V, f=1MHz		-	675	-	pF
Output Capacitance	C _{Oss}			-	22	-	pF
Reverse Transfer Capacitance	C _{rss}			-	13	-	pF
Total Gate Charge	Q _g	V _{CC} =480V, I _C =7A V _{GE} =15V		-	28	-	nC
Gate to Emitter Charge	Q _{ge}			-	8	-	nC
Gate to Collector Charge	Q _{gc}			-	13	-	nC
Short circuit collector current Max.1000 short circuits Time between short circuits: ≥1.0s	I _{C(SC)}	V _{GE} =15V,V _{CC} ≤400V, t _{sc} ≤5us,T _J ≤150°C		-	34	-	A
Switching Characteristics							
Turn-on Delay Time	t _{d(ON)}	V _{CC} =400V,I _C =7A V _{GE} =0/15V, R _g =5Ω Inductive Load		-	20	-	ns
Rise Time	t _r			-	15	-	ns
Turn-Off Delay Time	t _{d(OFF)}			-	73	-	ns
Fall Time	t _f			-	18	-	ns
Turn-On Switching Loss	E _{on}			-	0.21	-	mJ
Turn-Off Switching Loss	E _{off}			-	0.10	-	mJ
Total Switching Loss	E _{ts}			-	0.31	-	mJ

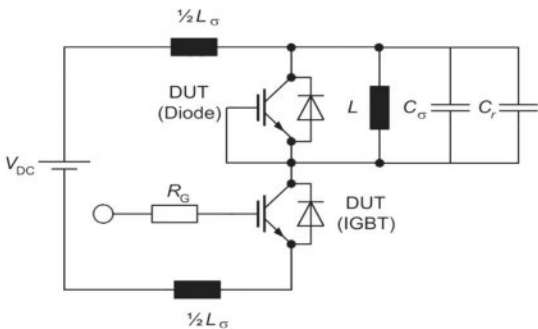
Electrical Characteristics of the Diode (Tc= 25°C unless otherwise specified):

Parameter	Symbol	Test Conditions	Rating			Units
			Min	Typ	Max	
Diode Forward Voltage	V _{FM}	I _F =7A	-	1.5	1.9	V
Reverse Recovery Time	T _{rr}	I _F =7A,di/dt=200A/uS	-	230	-	ns
Diode Peak Reverse Recovery Current	I _{RRM}		-	3.5	-	A
Reverse Recovery Charge	Q _{rr}		-	0.44	-	uC
Pulse width ttp≤380μs,δ≤2%						

Test Circuit

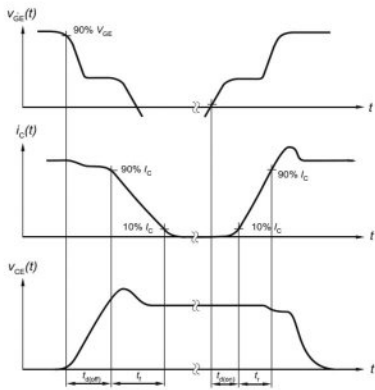


Gate Charge Test Circuit

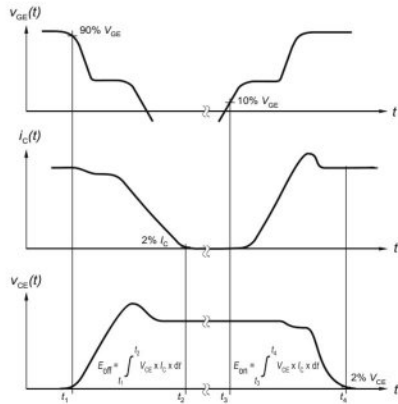


Switch Time Test Circuit

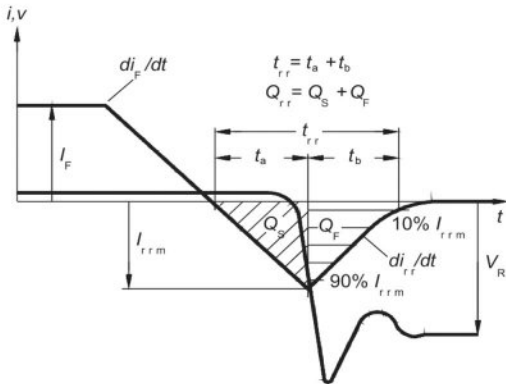
Switching characteristics



definition of switching times

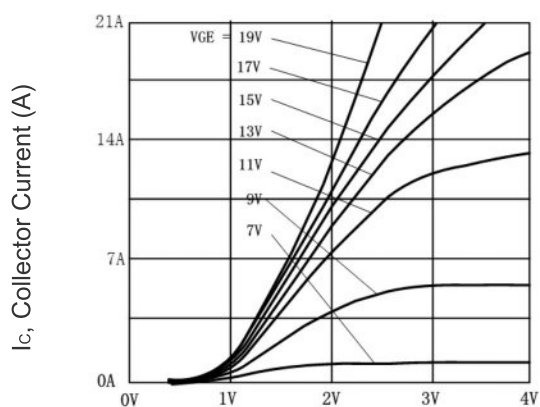


definition of switching losses

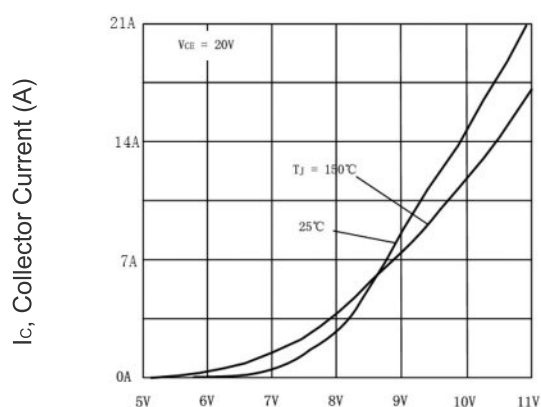


Definition of diode switching characteristics

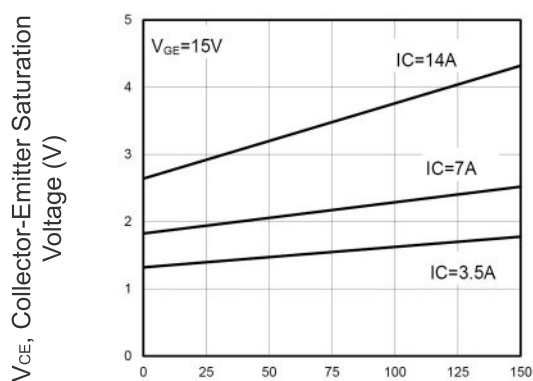
Typical Electrical and Thermal Characteristics



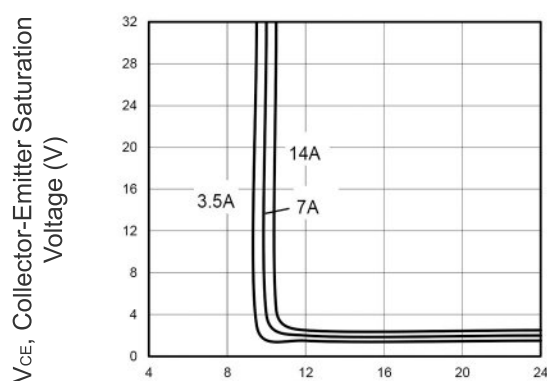
V_{CE} , Collector-Emitter Voltage (V)
Figure 1 Output Characteristics



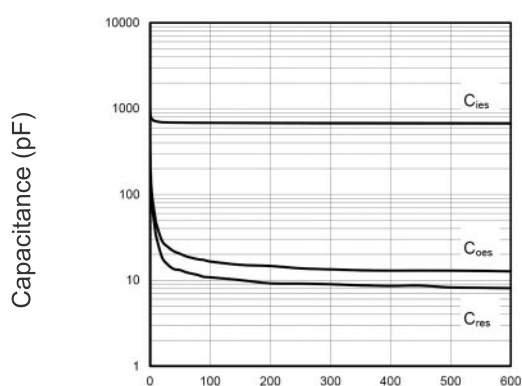
V_{GE} , Gate-Emitter Voltage (V)
Figure 2 Transfer Characteristics



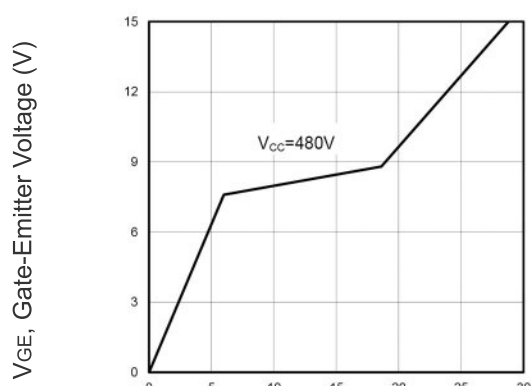
T_J , Junction Temperature ($^{\circ}\text{C}$)
Figure 3 V_{CEsat} vs. Case Temperature



V_{GE} , Gate-Emitter Voltage (V)
Figure 4 Saturation Voltage vs. V_{GE}



V_{CE} , Collector-Emitter Voltage (V)
Figure 5 Capacitance Characteristics



Q_G , Total Gate Charge (nC)
Figure 6 Gate charge waveform

Typical Electrical and Thermal Characteristics

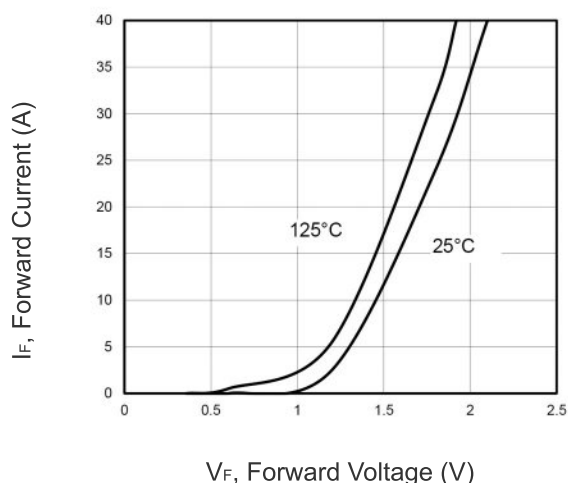


Figure 7 Forward Characteristics

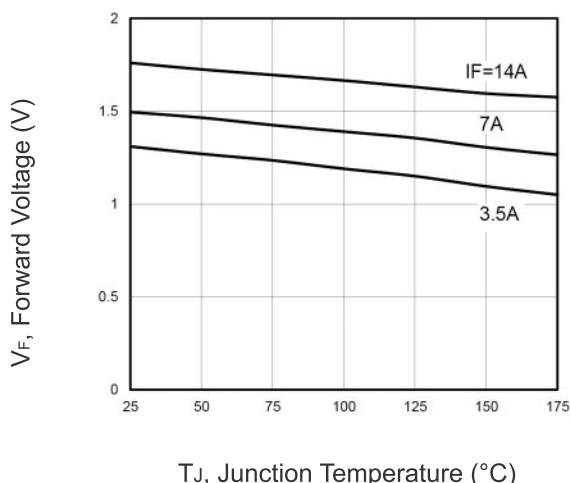


Figure 8 V_F vs. Temperature

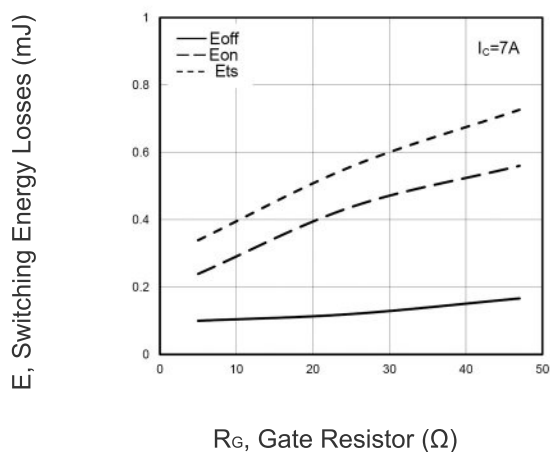


Figure 9 Typical Switching Times as a Function of Gate Resistor

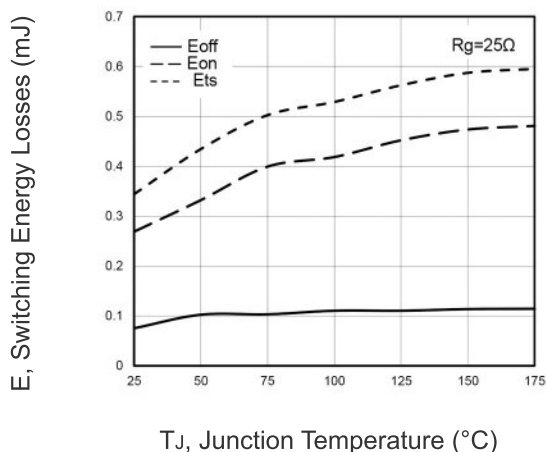


Figure 10 Typical Switching Times as a Function of Junction Temperature

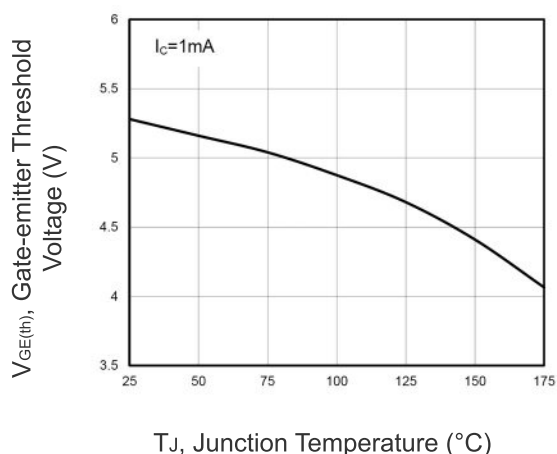


Figure 11 Gate-emitter Threshold Voltage as a Function of Junction Temperature

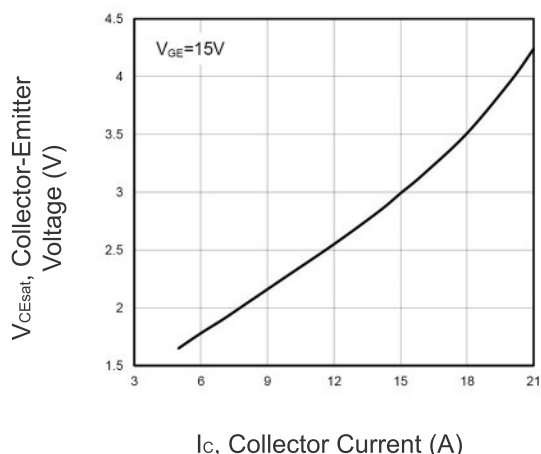


Figure 12 Typical Collector-emitter Saturation Voltage as a function of Collector Current

Typical Electrical and Thermal Characteristics

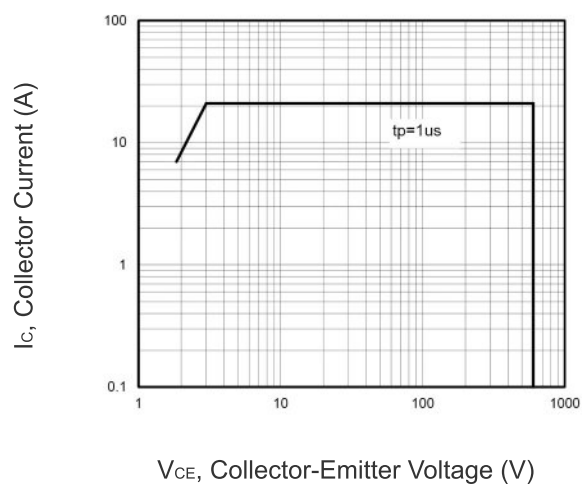
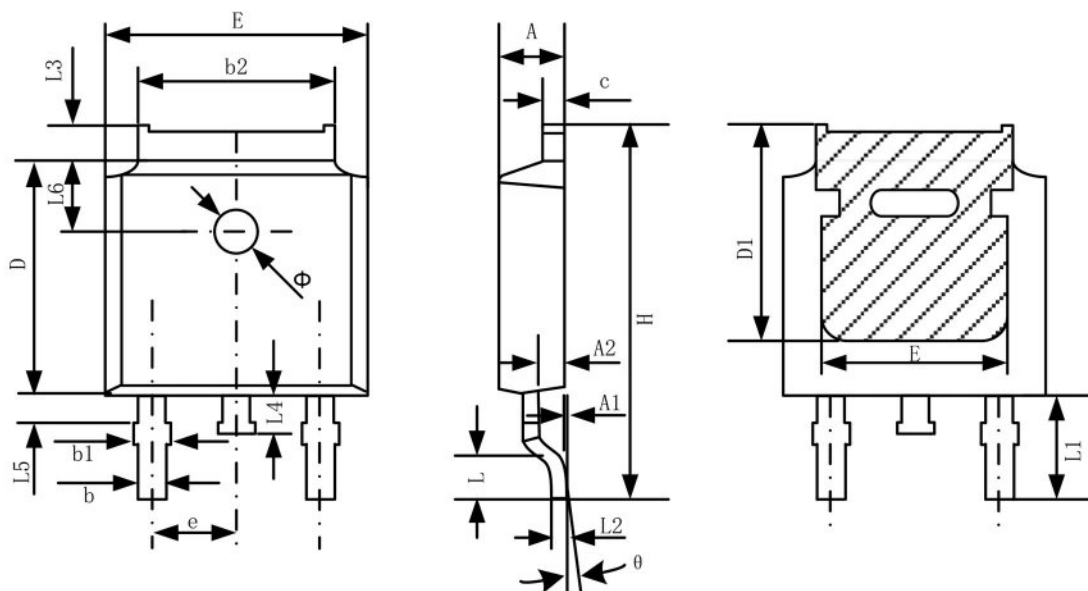


Figure 13 Forward Bias Safe Operating Area

TO-252-2 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.38	0.087	0.094
A1	0.00	0.10	0.000	0.004
A2	0.90	1.10	0.035	0.043
b	0.72	0.85	0.028	0.033
b1	0.72	0.90	0.028	0.035
b2	5.13	5.46	0.202	0.215
c	0.47	0.60	0.019	0.024
D	6.00	6.20	0.236	0.244
D1	5.25	--	0.207	--
E	6.50	6.70	0.256	0.264
E1	4.70	--	0.185	--
e	2.19	2.39	0.086	0.094
H	9.80	10.40	0.386	0.409
L	1.40	1.70	0.055	0.067
L1	2.90 REF		0.114 REF	
L2	0.508 BSC		0.020 BSC	
L3	0.90	1.25	0.035	0.049
L4	0.60	1.00	0.024	0.039
L5	0.15	0.75	0.006	0.030
L6	1.80 REF		0.071 REF	
Φ	1.20	1.40	0.047	0.055
θ	0°	8°	0°	0.31°

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